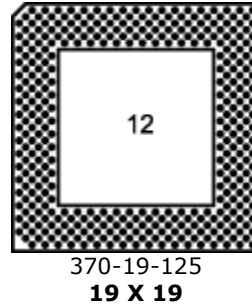
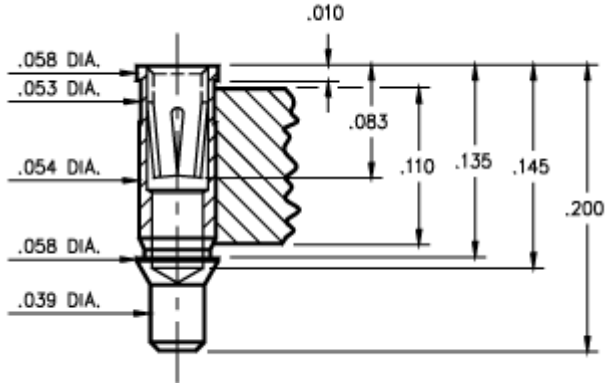




Product Number: 513-93-370-19-125085



Description:

PGA Socket
Surface Mount
Surface Mount
Accepts .015-.025" Leads

Plating Code:

93

Shell Plating:

200 μ" Tin/Lead(93/7) over 100 μ" Nickel

Inner Contact Plating:

30 μ" Gold over 50 μ" Nickel

Table with 3 columns: # Of Pins, Mill-Max Part Number, RoHS Compliant

370

513-93-370-19-125085

NO

CONTACT:

Contact Used: #43, Ultra Lite Force 6 Finger Contact

Current Rating = 3 Amps

BERYLLIUM COPPER ALLOY 172 (UNS C17200) per ASTM B 194

Properties of BERYLLIUM COPPER:

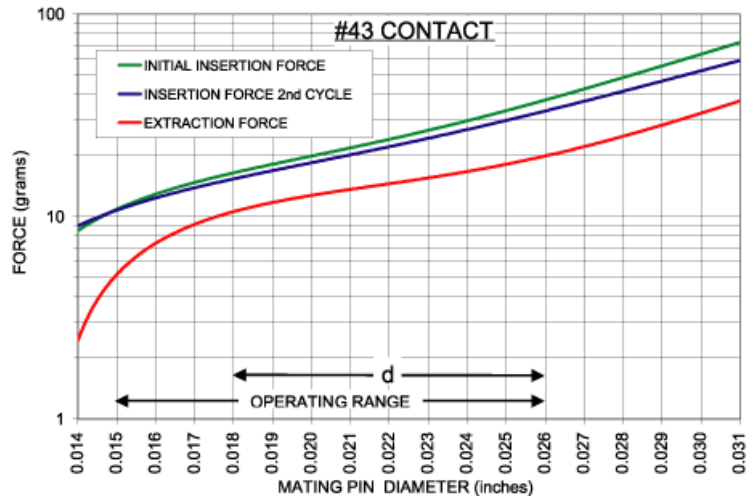
- Chemical composition: Cu 98.1%, Be 1.9%
Temper as stamped: TD01

Properties after heat treatment (TH01):

- Hardness: 36-43 Rockwell C
Mechanical Life: 100 Cycles Min.
Density: .298 lbs/in3
Electrical Conductivity: 22% IACS*
Resistance: 10 miliohms Max
Operating Temperature: -55°C/+125°C
Melting point: 980°C/865°C (liquidus/solidus)
Stress Relaxation†: 96% of stress remains after 1,000 hours @ 100 °C ; 70% of stress remains after 1,000 hours @ 200 °C

*International Annealed Copper Standard, i.e. as a % of pure copper.

†Since BeCu loses its spring properties over time at high temperatures; it is rated for continuous use up to 150°C. For applications up to 300°C, Mill-Max offers many contacts in Beryllium Nickel. Contact Tech Support for more info.



LOOSE PIN:

Loose Pin Used: 1385

BRASS ALLOY (UNS C36000) per ASTM B 16**Properties of BRASS ALLOY:**

- Chemical composition: Cu 61.5%, Zn 35.4%, Pb 3.1%†
- Hardness as machined: 80-90 Rockwell B
- Density: .307 lbs/in³
- Electrical conductivity: 26% IACS*
- Melting point: 900°C/885°C (liquidus/solidus)

†(3 to 4% lead is used to permit "free machining" and is permitted by EC Directive 2002/95Annex 6; so all pin materials are RoHS compliant)

*International Annealed Copper Standard, i.e. as a % of pure copper.

INSULATOR INFORMATION:**PCT Polyester**, (Thermx CG933, black)

High Temperature

Properties of PCT Polyester:

- Brand: Thermx
- Grade: CG-933
- Rated voltage: 100 VRMS/150 VDC
- Insulation resistance: 10,000 Megaohms min.
- Material Heat Deflection Temp (per ASTM D 648): 529°F (276°C) @ 66 psi
- Dielectric strength: 1000 VRMS min. (700 VRMS min. for series 117 Shrink DIP)

Note: Materials above 446°F (230°C) are considered suitable for "eutectic" reflow soldering, above 500°F (260°C) for "lead-free" reflow soldering.